

IN THE SPECIFICATION:

Please replace the title of the invention on Page 1 as follows:

**DIE-TO-DIE CONNECTION METHOD AND ASSEMBLIES
AND PACKAGES INCLUDING DICE SO CONNECTED**

Please replace the title of the invention on page 2 as follows:

**DIE-TO-DIE CONNECTION METHOD AND ASSEMBLIES
AND PACKAGES INCLUDING DICE SO CONNECTED**

Please replace Paragraph [0008] as follows:

a [0008] Keeping in mind the trend toward faster computers and other electronic devices, the use of intermediate conductive elements, such as wire bonds, and the conductive traces of carrier substrates to electrically connect the semiconductor dice of a multi-chip module is somewhat undesirable since the electrical paths of these types of connections are typically lengthy and, consequently, limit the speed with which the semiconductor dice of the multi-chip module may communicate with one another. The affects that these types of connections in conventional multi-chip modules have on the speed at which an electronic device, such as a computer, operates are particularly undesirable when one of the semiconductor dice of the multi-chip module is a microprocessor and the other semiconductor dice of the multi-chip module are semiconductor devices with which the microprocessor should quickly communicate.

[Please replace Paragraph [0009] as follows:]

[0009] The so-called system-on-a-chip (SOC) has been developed to increase the speed with which two semiconductor devices, such as a logic device (e.g., a microprocessor) and a memory device, communicate. Each of the semiconductor devices of a SOC structure are fabricated on the same substrate, providing very short connections with reduced contact resistance between two or more devices. The speed with which the two devices communicate is,

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therefore, increased relative to the speeds with which the separate semiconductor devices of conventional assemblies communicate.

Please replace Paragraph [0041] as follows:

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[0041] As corresponding bond pads 14 and 24 are electrically connected to one another by way of conductive structures 28, the physical lengths of electrical circuits including conductive structures 28 are much shorter than the physical lengths of circuits including wire bonds or conductive traces of carrier substrates, as have been employed in conventional multi-chip modules. Accordingly, first semiconductor die 10 may communicate with connected semiconductor dice, such as second semiconductor die 20, at much faster rates than are possible with conventional multi-chip modules.
